



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

HP TouchSmart 7320 Series PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm MB, scalar, sidekey, webcam, b-cas, converterboard, DSP board, Graphic card	8
Batteries	All types including standard alkaline and lithium coin or button style batteries	7
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps LED Panel	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	Power supply case parts	2
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing		0

refractory ceramic fibers		
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw drover	2# X10
Screw driver	1# X10
knife	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

- Please refer to the 3.1.2 disassemble hinge and real cover
- Please refer to the 3.1.3 disassemble the stand
- Please refer to the 3.1.4 Remove MB shielding
- Please refer to the 3.1.5 disassemble HDD & ODD
- Please refer to the 3.1.6 disassemble vesa mount
- Please refer to the 3.1.7 disassemble Speaker
- Please refer the 3.1.8/9/10 disassemble CPU/Mxm/thermal module/system fan
- Please refer to 3.1.11 disassemble converter & DSP board.
- Please refer to 3.1.12 disassemble webcam
- Please refer to 3.1.13 disassemble wireless card
- Please refer to 3.1.14 disassemble TV card
- Please refer to 3.1.15 disassemble MB and MB battery
- Please refer to 3.1.16 disassemble CPU & DDR.
- Please refer to 3.1.17 disassemble Base pan, panel and touch module.
- Please refer to 3.1.18 disassemble the battery on keyboard/mouse/remote control.
- Please refer to 3.1.19 disassemble power supply
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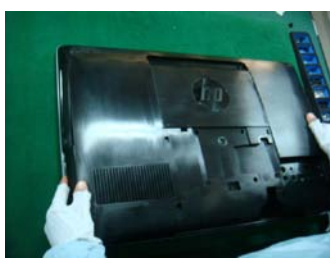
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Figure 1 : Mechanical parts disassembly

- 1) Place the system

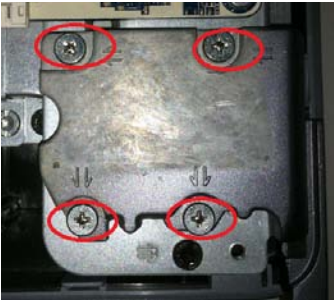


2) Disassemble hinge cover and rear cover.
Remove the screws with circle in red.



3) Disassemble stand

Remove four screws on both left and right so you can remove stand with two hands.



4) Disassemble MB shielding
Remove the screws with circles in red.

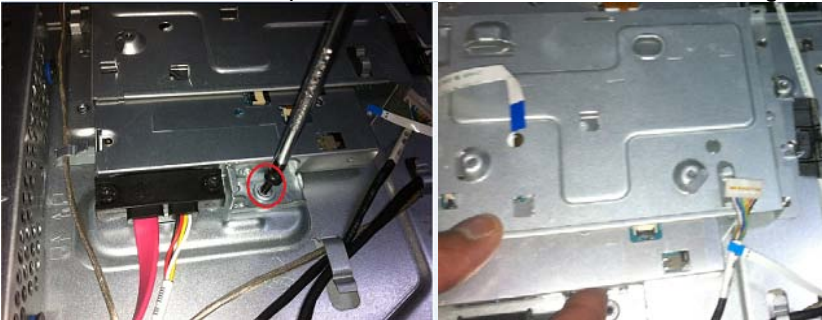


5) Disassemble HDD & ODD

Remove one screw from HDD and pull backward to disengage the HDD from base pan.

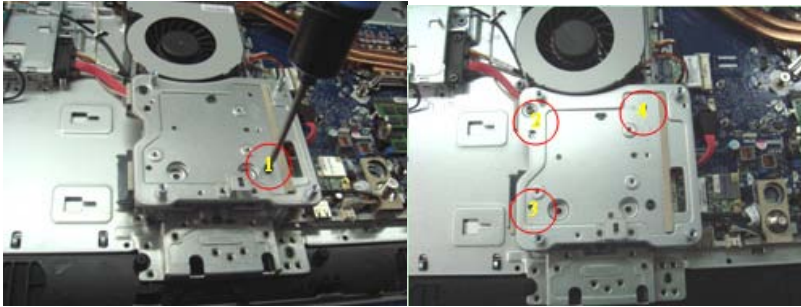


Remove one screw and push ODD forward to slide from ODD cage.



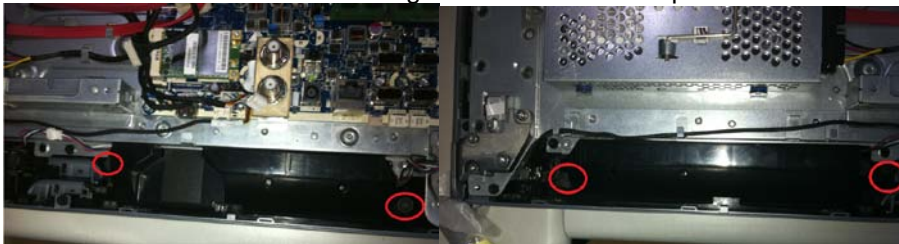
6) Disassemble for VESA mount

Remove the following screws that have circled in red.



7) Disassemble speaker

Remove two screws from left and right. Also remove the speaker cable in order to take out two speakers from system.



8) Disassemble CPU thermal module

Remove five screws and remove away the thermal module.



9) Disassemble MXM thermal module and remove the graphic card (with Graphic card module)

Remove five screws to remove the thermal module and disengage the graphic card from slot.



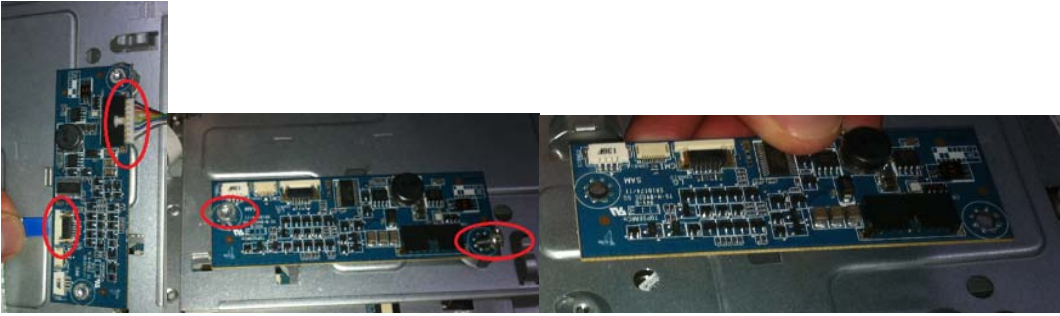
10) Disassemble FAN

Remove three screws and remove one cable to disassemble the fan.

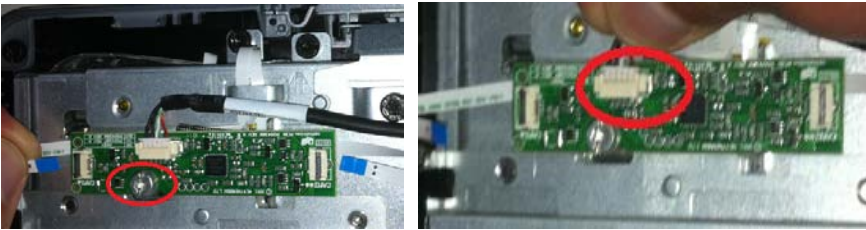


11) Disassemble Converter board and DSP board

Remove two cable and screws to disassemble the CVB.



Remove three cables and one screw to disengage the board from basepan.



12) Disassemble webcam

Remove the cable and screw in order to disengage the webcam module and mechanical parts.



13) Disassemble Wireless card

Remove one screw and two cables in order to remove wireless card.



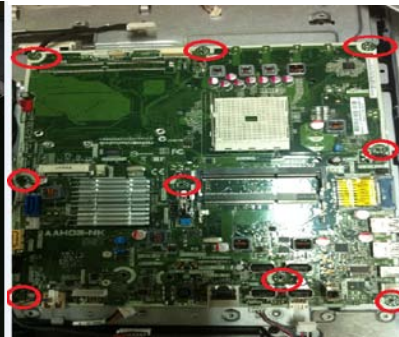
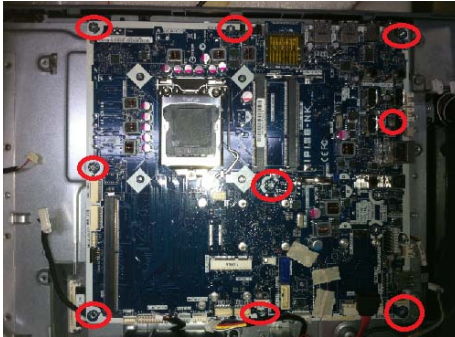
14) Remove TV card

Remove one screw and two connectors to remove the TV card.

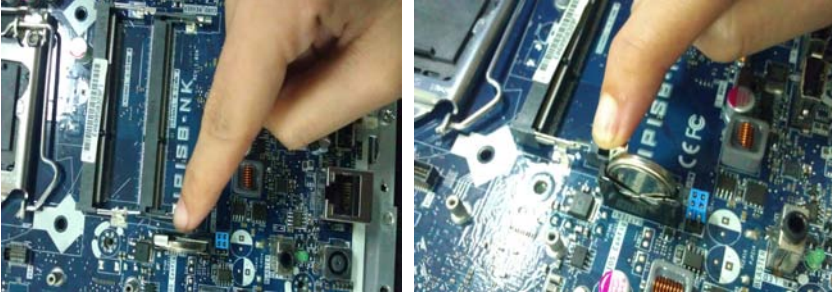


15) Remove MB & MB battery

Remove 9 screws to disassemble the MB.



Pull backward the clip to release the battery



16) Disassemble CPU and DDR
Remove the CPU by releasing the hook.



Pull both clips outward that holding the memory to remove the DDR



17) Separate BASE pan and touch module

Remove the screw with M4 x8 and M3 x5 to separate the base pan and touch glass.



18) Remove Mouse/Keyboard Battery/MB



19) Remove power supply

